

SANYO Semiconductors DATA SHEET

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LC717A10AJ — Capacitance-Digital-Converter LSI for Electrostatic Capacitive Touch Sensors

Overview

The LC717A10AJ is a high-performance and low-cost capacitance-digital-converter LSI for electrostatic capacitive touch sensor, especially focused on usability.

It has 16 channels capacitance-sensor input. This makes it ideal for use in the products that need many switches. Since the calibration function and the judgment of ON/OFF are automatically performed in LSI internal, it can make

development time more short. A detection result (ON/OFF) for each input can be read out by the serial interface (I²C compatible bus or SPI).

Also, measurement value of each input can be read out as 8-bit digital data. Moreover, gain and other parameters can be adjusted using serial interface.

Features

- Detection system: Differential capacitance detection (Mutual capacitance type)
- Input capacitance resolution: Can detect capacitance changes in the femto Farad order
- Measurement interval (16 differential inputs): 30ms (Typ) (at initial configuration),

6ms (Typ) (at minimum interval configuration)

- External components for measurement: Not required
- Interface: I^2C^* compatible bus or SPI selectable.
- Current consumption: $570\mu A$ (Typ) (V_{DD} = 2.8V), 1.3mA (Typ) (V_{DD} = 5.5V)
- Supply voltage: 2.6V to 5.5V
- Detection operations: Switch
- Packages: SSOP30

* I²C Bus is a trademark of Philips Corporation.

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Specifications

Absolute Maximum Ratings at $Ta = +25^{\circ}C$

Parameter	Symbol	Ratings (V _{SS} = 0V)	Unit	Remarks
Supply voltage	V _{DD}	-0.3 to +6.5	V	
Input voltage	VIN	-0.3 to V _{DD} +0.3	V	*1
Output voltage	VOUT	-0.3 to V _{DD} +0.3	V	*2
Power dissipation	Pd max	160	mW	Ta = +105°C, Mounted on a substrate *3
Storage temperature	Tstg	-55 to +125	°C	

*1) Apply to Cin0 to 15, Cref, CrefAdd, nRST, SCL, SDA, SA0, SA1, SCK, SI, nCS

*2) Apply to Cdrv, SDA, SO, INTOUT

*3) Single-layer glass epoxy board (76.1×114.3×1.6t mm)

Recommended Operating Conditions

Parameter	Symbol	Conditions	min	typ	max	Unit	Remarks
Operating supply voltage	V _{DD}		2.6		5.5	V	
Supply ripple + noise	Vpp				±20	mV	*1
Operating temperature	Topr		-40	25	105	°C	

*1) We recommend connecting large and small capacitance between $V_{\mbox{DD}}$ and $V_{\mbox{SS}}$.

In this case, the small capacitance is equal to or more than 0.1µF, and layout nearby LSI.

Electrical Characteristics at $V_{SS} = 0V$, $V_{DD} = 2.6$ to 5.5V, Ta = -40 to $+105^{\circ}C$

* Unless otherwise specified, the Cdrv drive frequency is $f_{CDRV} = 143 \text{kHz}$.

* Not tested at low temperature before shipment.

Parameter	Symbol	Conditions	min	typ	max	Unit	Remarks
Capacitance detection resolution	N				8	bit	
Output noise RMS	N _{RMS}	minimum gain setting			±1.0	LSB	*1 *3
Input offset capacitance adjustment range	CoffRANGE			±8.0		pF	*1 *3
Input offset capacitance adjustment resolution	CoffRESO			8		bit	
Cin offset drift	CinDRIFT	minimum gain setting			±8	LSB	*1
Cin detection sensitivity	CinSENSE	minimum gain setting	0.04		0.12	LSB/fF	*2
Cin pin leak current	I _{Cin}	Cin = Hi-Z		±25	±500	nA	
Cin allowable parasitic input capacitance	Cin _{SUB}	Cin against V _{SS}			30	pF	*1 *3
Cdrv drive frequency	^f CDRV		100	143	186	kHz	
Cdrv pin leak current	ICDRV	Cdrv = Hi-Z		±25	±500	nA	
nRST minimum pulse width	^t NRST		1			μs	*1
Power-on reset time	^t POR				20	ms	*1
Power-on reset operation condition: Hold time	^t POROP		10			ms	*1
Power-on reset operation condition: Input voltage	VPOROP				0.1	V	*1
Power-on reset operation condition: Power supply rise rate	tVDD	0V to V _{DD}	1			V/ms	*1

Continued to the next page.

Parameter	Symbol	Conditions	min	typ	max	Unit	Remarks
Pin input voltage	∨ _{IH}	V _{IH} High input					
	VIL	Low input			0.2V _{DD}	V	*1 *4
Pin output voltage	VOH	High output (I _{OH} = +3mA)	0.8V _{DD}				*5
	VOL	Low output (I _{OL} = -3mA)			0.2V _{DD}	V	5
SDA pin output voltage	V _{OL} I ² C	SDA Low output (I _{OL} = -3mA)			0.4	V	
Pin leak current	ILEAK				±1	μΑ	*6
Current consumption	IDD	When initial setting and non-touch V _{DD} = 2.8V		570	700	μΑ	*1 *3
		When initial setting and non-touch VDD = 5.5V		1.3	1.6	mA	*1 *3
	ISTBY	During Sleep process			1	μA	*3

*1) Design guarantee values (not tested before shipment)

*2) Measurements conducted using the test mode in the LSI

*4) Apply to nRST, SCL, SDA, SA0, SA1, SCK, SI, nCS

*5) Apply to Cdrv, SO, INTOUT

*6) Apply to nRST, SCL, SDA, SA0, SA1, SCK, SI, nCS

^{*3)} Ta = +25°C

Parameter	Symbol	Pin Name	Conditions	min	typ	max	Unit	Remarks
SCL clock frequency	^f SCL	SCL				400	kHz	
START condition hold time	^t HD;STA	SCL		0.6				
	SDA 0.8				μs			
SCL clock low period	^t LOW	SCL		1.3			μs	
SCL clock high period	^t HIGH	SCL		0.6			μs	
Repeated START condition	^t SU;STA	SCL		0.6				*1
setup time		SDA		0.6			μs	Ι
Data hold time	^t HD;DAT	SCL		0		0.9		
		SDA		0		0.9	μs	
Data setup time	^t SU;DAT	SCL		100				*1
		SDA		100			μs	-
SDA, SCL rise/fall time	t _r / t _f	SCL				300		*1
		SDA				500	μs	
STOP condition setup time	^t SU;STO	SCL		0.6				
		SDA		0.6			μs	
STOP-to-START bus release	^t BUF	SCL		1.3				*1
time		SDA		1.3			μs	I

I²C Compatible Bus Timing Characteristics at $V_{SS} = 0$, $V_{DD} = 2.6$ to 5.5V, Ta = -40 to $+105^{\circ}C$ *Not tested at low temperature before shipment

*1) Design guarantee values (not tested before shipment)

SPI Bus Timing Characteristics at V_{SS} = 0, V_{DD} = 2.6 to 5.5V, Ta = -40 to +105°C

*Not tested at low temperature before shipment

Parameter	Symbol	Pin Name	Conditions	min	typ	max	Unit	Remarks	
SCK clock frequency	^f SCK	SCK				5	MHz		
SCK clock Low time	^t LOW	SCK		90			ns	*1	
SCK clock High time	tHIGH	SCK		90			ns	*1	
Input signal rise/fall time	t _r / t _f	nCS							
		SCK			300	ns	*1		
		SI							
nCS setup time	S setup time t _{SU;NCS} nCS 90					*1			
	,	SCK		90			ns	I	
SCK clock setup time	^t SU;SCK	nCS		90			ns	*1	
		SCK		90			115	1	
Data setup time	^t SU;SI	SCK		20			ns	*1	
		SI		20			115	1	
Data hold time	^t HD;SI	SCK		30			ns	*1	
		SI		50			115	1	
nCS hold time	^t HD;NCS	nCS		90			ns	*1	
		SCK		90			115	1	
SCK clock hold time	^t HD;SCK	nCS		90			ns	*1	
		SCK		90			115		
nCS standby pulse width	^t CPH	nCS		90			ns	*1	
Output high impedance time	^t CHZ	nCS						*4	
from nCS	-	SO				80	ns	*1	
Output data determination time	t _v	SCK				00		*1	
		SO				80	ns	~1	
Output data hold time	tHD;SO	SCK						*4	
		SO		0			ns	*1	
Output low impedance time	^t CLZ	SCK		0				*1	
from SCK clock		SO		0			ns	- 1	

*1) Design guarantee values (not tested before shipment)

Power-on Reset (POR)

When power is turned on, power-on reset is enabled inside the LSI and its state is released after a certain power-on reset time, t_{POR} . Power-on Reset operation condition; Power supply rise rate t_{VDD} must be at least 1V/ms. Since INTOUT pin changes from "High" to "Low" at the same time as the released of power-on reset, it is possible to verify the timing of release of power-on reset externally.

During power-on reset, Cin, Cref and CrefAdd are unknown.

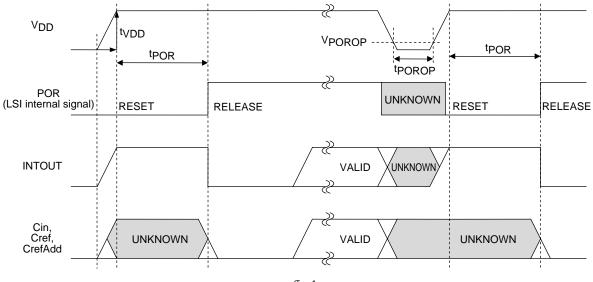
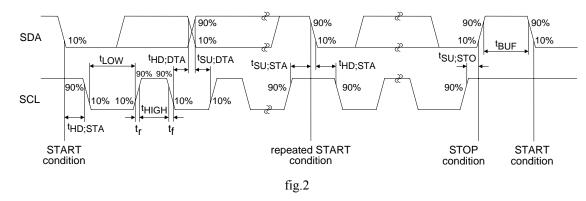


fig.1

I²C Compatible Bus Data Timing



I²C Compatible Bus Communication Formats

• Write format (data can be written into sequentially incremented addresses)

START	Slave Address	Write=L	ACK	Register Address (N)	ACK	Data written to Register Address (N)	ACK	Data written to Register Address (N+1)	ACK	STOP
			Slave		Slave		Slave		Slave	
				t	fig.3					

• Read format (data can be read from sequentially incremented addresses)

START	Slave Address	Write=L	ACK	Register Address (N)	ACK				
			Slave		Slave				
RESTART	Slave Address	Read=H	ACK	Data read from Register Address (N)	ACK	Data read from Register Address (N+1)	ACK	Data read from Register Address (N+2)	NACK STOP
			Slave		Master	r	Master		Master
				f	fig.4				

I²C Compatible Bus Slave Address

Selection of two kinds of addresses is possible through the SA0 and SA1 terminals.

SA1 input	SA0 input	7bit slave address	Binary notation	8bit slave address
Low	Low	0x16	00101100b (Write)	0x2C
			00101101b (Read)	0x2D
Low	High	0x17	00101110b (Write)	0x2E
			00101111b (Read)	0x2F
High	Low	0x18	00110000b (Write)	0x30
			00110001b (Read)	0x31
High	High	0x19	00110010b (Write)	0x32
			00110011b (Read)	0x33

SPI Data Timing (SPI Mode 0 / Mode 3)

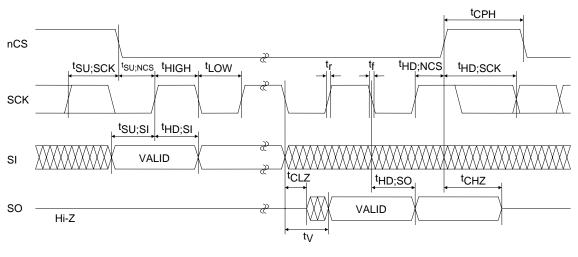


fig.5

SPI Communication Formats (Example of Mode 0)

• Write format (data can be written into sequentially incremented addresses with preserving nCS = L)

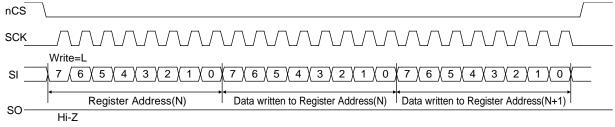
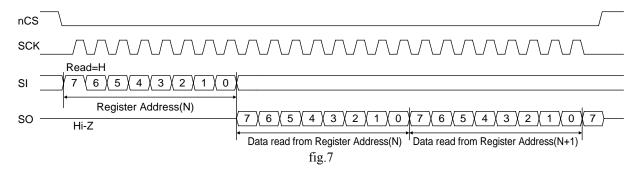


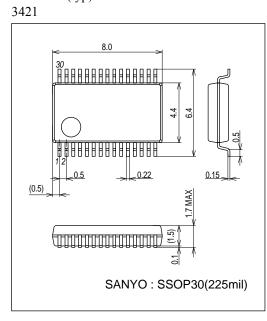
fig.6

• Read format (data can be read from sequentially incremented addresses with preserving nCS = L)



Package Dimensions [LC717A10AJ]

unit : mm (typ)

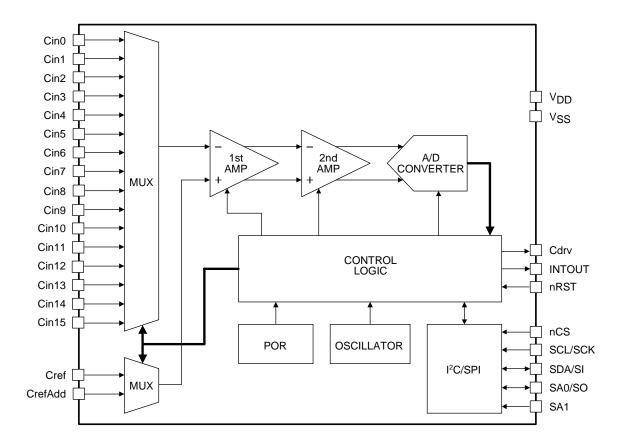


Pin Assignment

Pin Name	Pin No.	Pin Name
V _{DD}	16	Cref
V _{SS}	17	CrefAdd
Non Connect *1	18	Cdrv
Cin4	19	INTOUT
Cin5	20	SA1
Cin6	21	SCL/SCK
Cin7	22	SDA/SI
Cin8	23	SA0/SO
Cin9	24	nCS
Cin10	25	nRST
Cin11	26	Non Connect *1
Cin12	27	Cin0
Cin13	28	Cin1
Cin14	29	Cin2
Cin15	30	Cin3
	VDD VSS Non Connect *1 Cin4 Cin5 Cin6 Cin7 Cin8 Cin9 Cin10 Cin12 Cin13 Cin14	V _{DD} 16 V _{SS} 17 Non Connect *1 18 Cin4 19 Cin5 20 Cin6 21 Cin7 22 Cin8 23 Cin9 24 Cin10 25 Cin11 26 Cin12 27 Cin13 28 Cin14 29

*1) connect to GND when mounted

Block Diagram



LC717A10AJ is capacitance-digital-converter LSI capable of detecting changes in capacitance in the order of femto Farads. It consists of an oscillation circuit that generates the system clock, a power-on reset circuit that resets the system when the power is turned on, a multiplexer that selects the input channels, a two-stage amplifier that detects the changes in the capacitance and outputs analog-amplitude values, a A/D converter that converts the analog-amplitude values into digital data, an I²C compatible bus or a SPI that enables serial communication with external devices and a control logic that controls the entire chip.

Pin Functions Pin Name I/O **Pin Functions** Pin Type Cin0 I/O Capacitance sensor input Cin1 I/O Capacitance sensor input Cin2 I/O Capacitance sensor input Cin3 I/O Capacitance sensor input Capacitance sensor input Cin4 I/O Cin5 I/O Capacitance sensor input VDD Cin6 I/O Capacitance sensor input AMP Cin7 I/O Capacitance sensor input R Cin8 I/O Capacitance sensor input Cin9 I/O Capacitance sensor input Capacitance sensor input Cin10 I/O Cin11 I/O Capacitance sensor input Vss Cin12 I/O Capacitance sensor input Buffer Cin13 I/O Capacitance sensor input Cin14 I/O Capacitance sensor input Cin15 I/O Capacitance sensor input Cref I/O Reference capacitance input CrefAdd I/O Reference capacitance input for addition VDD 0 Cdrv Output for capacitance sensors drive Buffer INTOUT 0 Interrupt output Vss $\overline{}$ Clock input (I²C) Д SCL/SCK I VDD / Clock input (SPI) Interface selection nCS I / Chip select inverting input (SPI) R nRST I External reset signal inverting input SA1 I Slave address selection (I²C) Vss # VDD R Data input and output (I²C) SDA/SI I/O / Data input (SPI) k

Vss

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Pin Name	I/O	Pin Functions	Pin Type
SA0/SO	1/0	Slave address selection (I ² C) / Data output (SPI)	V _{DD} R V _{SS} m Buffer
V _{DD}		Power supply (2.6V to 5.5V) *1	
VSS		Ground (Earth) *1 *2	

*1) Inserting a high-valued capacitor and a low-valued capacitor in parallel between V_{DD} and V_{SS} is recommended. In this case, the small-valued capacitor should be at least 0.1µF, and is mounted near the LSI.

*2) When VSS terminal is not grounded in battery-powered mobile equipment, detection sensitivity may be degraded.

Details of Pin Functions

•Cin0 to Cin15

These are the capacitance-sensor-input pins. These pins are used by connecting them to the touch switch pattern. Cin and the Cdrv wire patterns should be close to each other. By doing so, Cdrv and Cin patterns are capacitively coupled. Therefore, LSI can detect capacitance change near each pattern as 8bit digital data.

However, if the shape of each pattern or the capacitively coupled value of Cdrv is not appropriate, it may not be able to detect the capacitance change correctly.

In this LSI, there is a two-stage amplifier that detects the changes in the capacitance and outputs analog-amplitude values. Cin0 to Cin15 are connected to the inverting input of the 1st amplifier.

During measurement process, channels other than the one being measured are all in "Low" condition. Leave the unused terminals open.

•Cref, CrefAdd

These are the reference-capacitance-input pins. These are used by connecting to the wire pattern like Cin pins or are used by connecting any capacitance between this pin and Cdrv pin.

In this LSI, there is a two-stage amplifier that detects the changes in the capacitance and outputs analog-amplitude values. Cref is connected to the non-inverting input of the 1st amplifier.

Due to the parasitic capacitance generated in the wire connections of Cin pins and their patterns, as well as the one generated between the wire patterns of Cin and Cdrv pins, Cref may not detect capacitance change of each Cin pin accurately. In this case, connect an appropriate capacitance between Cref and Cdrv to detect capacitance change accurately.

However, if the difference between the parasitic capacitance of each Cin pin is extremely large, it may not detect capacitance change of each Cin pin correctly.

CrefAdd can be used as additional terminal for Cref. Leave the CrefAdd open if not in used.

•Cdrv

It is the output pin for capacitance sensors drive. It outputs the pulse voltage which is needed to detect capacitance at Cin0 to Cin15.

Cdrv and Cin wire patterns should be close to each other so that they are capacitively coupled.

●INTOUT

It is the interrupt-output pin.

It is used by connecting to a main microcomputer if necessary, and use as interrupt signal. (High Active) Leave the terminal open if not in used.

•SCL/SCK

Clock input $(I^2C) / Clock input (SPI)$

It is the clock input pin of the I²C compatible bus or the SPI depending on the mode of operation.

●nCS

Interface selection / Chip-select-inverting input (SPI)

Selection of I^2C compatible bus mode or SPI mode is through this terminal. After initialization, the LSI is automatically in I^2C compatible bus mode. To continually use I^2C compatible bus mode, fix nCS pin to "High". To switch to SPI mode after LSI initialization, change the nCS input "High" \rightarrow "Low". The nCS pin is used as the chipselect-inverting input pin of SPI, and SPI mode is kept until LSI is again initialized.

●nRST

It is the external-reset-signal-inverting-input pin. When nRST pin is "Low", LSI is in reset state. Each pin (Cin0 to 15, Cref, CrefAdd) is "Hi-Z" during reset state.

•SDA/SI

Data input and output (I²C) / Data input (SPI)

It is the data input and output pin of the I²C compatible bus or the data input pin of the SPI depending on the mode of operation.

•SA0/SO

Slave address selection (I²C) / Data output (SPI)

It is the slave address selection pin of the I^2C compatible bus or the data output pin of the SPI depending on the mode of operation.

●SA1

Slave address selection (I^2C)

It is the slave address selection pin of the I²C compatible bus. When SPI mode, connect to the SA1 pin to GND.

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